



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-10-17
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	Representative Title	AMS & IPD Material Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ITA18B1	MHO7*TAW018B	A	BO2A	2013-10-17
Amount	UoM	Unit type	ST ECOPACK Grade	
80.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.9 - 3.9 - 1.52	8	gull wing	
Comment	Package: SO 08 .15 JEDEC; MDF valid also for: (FG: ITA18B1RLH/ZM - CP: ITA18B1RL)			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	MHO7*TAW018B					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	3.443	mg	supplier	die	Silicon (Si)	7440-21-3		3.322	mg	964856	41525
				supplier	metallization	Aluminium (Al)	7429-90-5		0.048	mg	13941	600
				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.017	mg	4938	211
				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.022	mg	6390	275
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	580	25
				supplier	back side metallization	Gold (Au)	7440-57-5		0.006	mg	1743	75
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.026	mg	7552	325
Leadframe	Copper & its alloys	35.284	mg	supplier	alloy	Copper (Cu)	7440-50-8		34.056	mg	965197	425700
				supplier	alloy	Iron (Fe)	7439-89-6		0.801	mg	22702	10013
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.048	mg	1360	600
				supplier	alloy	Zinc (Zn)	7440-66-6		0.042	mg	1190	525
				supplier	metallization	Nickel (Ni)	7440-02-0		0.313	mg	8871	3913
				supplier	metallization	Palladium (Pd)	7440-05-3		0.013	mg	368	162
				supplier	metallization	Gold (Au)	7440-50-8		0.011	mg	312	137
Die attach	Other inorganic materials	1.068	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.972	mg	910112	12150
				supplier	glue or tape	acrylate	Proprietary		0.053	mg	49625	662
				supplier	glue or tape	Methacrylate	Proprietary		0.043	mg	40263	538
Bonding wire	Other inorganic materials	0.147	mg	supplier	wire	Copper (Cu)	7440-50-8		0.147	mg	1000000	1838
Encapsulation	Other inorganic materials	40.058	mg	supplier	mold compound	Epoxy Resin	25068-38-6		3.005	mg	75016	37563
				supplier	mold compound	Phenol Resin	29690-82-2		2.003	mg	50002	25038
				supplier	mold compound	Silica, vitreous	60676-86-0		34.69	mg	865994	433625
				supplier	mold compound	Carbon black	1333-86-4		0.2	mg	4993	2500
				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.16	mg	3995	2000